Dr. YVN Chandana

Assistant Professor

Education Qualifications: Doctor of Philosophy
Specialization: Electronic Packaging and Reliability

ADDRESS:
- B – Block -Room No -104

JNTUH ID:
7731-170202-105453

EMAIL:
yvnchandana_mct@mgit.ac.in

DATE OF JOINING:
20-08-2018

EXPERIENCE - 15 Years
- Teaching - 10
- Industry -05

SUMMARY:
- Publications - 10
- Conferences - 04

EVENTS:
- Organized - 03
- Attended - 40

Membership of Professional Bodies:

1. Life Member, Indian Society of Technical Education (ISTE)

Responsibilities Held at Institution Level:

1. Student Bus In-charge, coordinating and monitoring student transportation services.
2. Performing Campus Monitoring Duties to ensure discipline, safety, and smooth functioning of campus activities.
3. Undertaking Invigilation Duties for Internal Assessments, Mid-Semester Examinations, and End-Semester Examinations, ensuring adherence to examination.
4. Co-Ordinator for Music Club

Responsibilities Held at Department Level:

1. BOS member for UG Mechanical Engineering, Mechatronics and PG Mechatronics.
2. Continuously maintained and updated departmental documentation and records related to NBA Accreditation, Autonomous, and NAAC Accreditation requirements.
3. Functioning as Class In-charge, overseeing academic and administrative matters of the assigned class.
4. Monitored and mentored assigned students regularly to support their academic progress, performance improvement, and overall development.

Software Proficiency:

Abaqus, Ansys, SolidWorks, Creo, LabView, AutoCAD, KiCAD, JMP

Research Guidance:

Project guidance for UG students: 15 projects

Courses Handled at Under Graduate /Post Graduate Level:

UG: Design of Machine Members-I, Design of Machine members-II, Principles of Machine Design, CAD/CAM, Finite Element Methods, Mechanics of Solids, Engineering Mechanics.

Publications:

1. Venkata Naga Chandana Y, Venu Kumar N. (2025). A machine learning approach for evaluating drop impact reliability of solder joints in BGA packaging, Applied Computer Science, 21(3), 59–71. (ISSN 2353-6977)
2. Yagnamurthy, V. N. C., & Nathi, V. K. (2025). Board level solder joint analysis of ball grid array package under drop test using finite element methods. Matéria (Rio De Janeiro), 30, e20240798. (ISSN 1517-7076)

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3. Venkata Naga Chandana Y, Venu Kumar N. (2024). Experimental and Numerical Investigation of Solder Joint Reliability of Ball Grid Array Package under Board level Drop Test. Nanotechnology Perceptions, 20(6), 842-859. (ISSN 1660-6795)
4. Venkata Naga Chandana Y, Venu Kumar N. (2022). Drop test analysis of ball grid array package using finite element methods. Materials Today: Proceedings, 64 PP.675–679.
5. Y. Venkata Naga Chandana, N. Venu Kumar, "Parametric study of thermally induced warpage of FpBGA package using Finite Element Methods" Materials Today: Proceedings ISSN- 2214-7853, Volume 51, Part 1, May 2022, Pages 430-434
6. Y. Venkata Naga Chandana, N. Venu Kumar, Warpage Analysis of an Over Molded Chip Scale Electronic Package using Finite Element Method, Science, Technology and Development Journal, ISSN-0950-0707, Vol X, Issue III, March 2021, p620-625
7. Y Venkata Naga Chandana, Thermal Management and Parametric Study of Flip Chip BGA using Finite Element Methods, International Journal for Research in Applied Science & Engineering Technology, Volume 9 Issue VI June/2021 5518-5524, ISSN: 2321-9653
8. Venkata Naga Chandana. Y & Venu Kumar. N, Thermal Characterization Of Electronic Package With Non-uniform Power Maps, International Journal of Mechanical and Production Engineering Research and Development (IJMPERD), Vol. 10, Issue 3, Jun 2020, Pp8179-8190 ISSN (P): 2249–6890; ISSN (E): 2249–8001
9. Y.V.N. Chandana and C. Sravanthi, Optimization of Engine Efficiency by Reducing the weight of Connecting Rod by using Composite Material Carbon Fiber Epoxy, International Journal for Research in Applied Science & Engineering Technology. Vol. 6 Issue II, February 2018, pp 2046-2051
10. Y.V.N. Chandana and K.V Purushottam Reddy, Transient Thermal Analysis of AlSiCp Composite Disc Brake, International Journal of Computational Engineering Research.Vol.07 Issue.02 February – 2017 ,pp 29-33

Conferences:

1. Y Venkata Naga Chandana, "**Effect of Moisture on Drop Reliability of Leaded and Lead-Free Solder Joints of Ball Grid Array Package",** International Conference on Emerging Multifunctional Materials and Devices for Sustainable Technologies (IEMDST-2026), organized by the National Institute of Technology Goa held from 8–9 June 2026.
2. Y V N Chandana, "**Stress analysis of a Ball Grid Array Package using Finite Element Methods**" ICRAITMS-2021, 19th and 20th March 2021, Hyderabad.
3. YVN Chandana," Drop Test analysis of Ball Grid Array Package Using Finite Element Methods" ICAMIS-2022, 18th and 19th February 2022, Hyderabad.
4. Presented a Paper on "**Parametric study of thermally induced warpage of FpBGA package using Finite Element Methods**" in NICEST'21, March 2021 at MGIT.

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Events Organized:

FDPs/STTPs:

1. Two-Day Drone workshop "From Ground to Sky" 9-10 February 2026, In Association with ACIC CBIT.
2. Two-Day Hands-on Workshop on Fusion 360 In association with Design Labs.
3. Co-Ordinator for one week Online Short-Term Training Program (STTP) on "Recent Advances in Micro Electro Mechanical Systems (MEMS), Mechatronics and their Applications for future challenges" Slot-3 held from 24-29 August 2020.

Events Attended:

FDPs/STTPs:

1. ATAL Academy online FDP on "Sustainable Engineering" from 25-01-2021 to 29-1-2020
2. Attended AICTE sponsored one week online short-term training program "Recent Advances in Design and Development of Mechatronics and Robotic Systems" organized by Mechanical Dept, MGIT from 02-11-2020 to 07-11-2020.
3. Two weeks Faculty Development Program, sponsored by AICTE, on "Recent Advances in Design and Development of Mechatronics and Robotic Systems" organized by MGIT from 4th to 16th December 2017
4. Two week Faculty Development Program on "Effective Teaching and Learning" and Skill Enhancement Program" at K.G.Reddy College of Engineering and Technology during 14th -26th May 2018

Refresher Courses/ Workshops/ Webinars/ Seminars/Guest Lecture:

1. One-day workshop on "Significance of MATLAB in applications of emerging technologies" held on 26th June 2019 at CBIT.
2. One-day National seminar on "Teacher as Performer" held on 21st December, 2018 at MGIT
3. Five-day Workshop conducted in MGIT on "Faculty Enablement Program on Fusion 360" by AUTODESK during December 2016

Online Certifications:

1. NPTEL Course on "Electronic Packaging and Manufacturing" Jan-March 2026 with Elite certificate.
2. NPTEL Course on "Manufacturing of Composites" during Aug-Oct 2019 with Elite-Gold certificate
3. NPTEL Course on "Processing of Polymers and Polymer Composites" Jan-March 2020

Any Other Contribution:

1. Project guidance for UG students.
2. On-line FDP's attended: 20
3. On-line webinars attended: 20